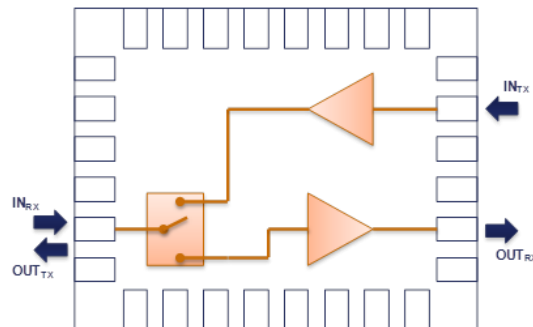


Advanced Information: AI2016

## 24.25-30.5GHz High Power Front End

### GaN & GaAs Monolithic Microwave IC SMD leadless package

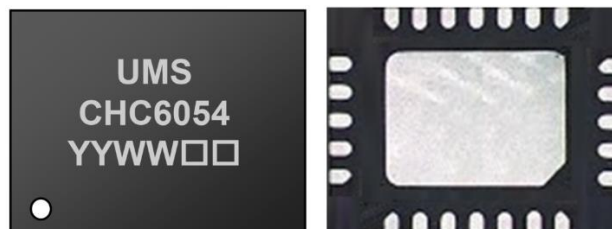


UMS develops a High Power Front-End (HPFE) featuring Transmit and Receive paths combined with In/Out Switch. This circuit operates in the 24.25-30.5GHz bandwidth. It is specially designed for telecommunication radio links. It typically exhibits a Receiver gain of 18dB with a low noise figure of 3.2dB, a Transmit gain of 28dB with 31dBm saturated output power. It features good linearity with an ACPR of 36dBc @23dBm average Pout with 56MHz modulation bandwidth and 4QAM.

This HPFE is realized on mixed technologies 150nm Gallium Nitride on Silicon Carbide (AlGaIn/GaN on SiC) and 150nm Gallium Arsenide (GaAs) - UMS proprietary technologies - and provided in a cost effective plastic package

It is well suited for :

- 5G mmw Mobile & Fixed Wireless Access  
24.25-27.5GHz,  
26.5-29.5 GHz,  
27.5-28.35 GHz
- M-MIMO / Phased array antennas
- Time Division Duplex systems



### Electrical Characteristics – TX Mode

Tamb.= +25°C, Vd12 = 25V, Vg12 set in order to get Id12 = 40mA

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	24.25		30.5	GHz
Gain	Linear Gain		28		dB
RL <sub>in</sub>	Input return loss		12		dB
RL <sub>out</sub>	Output return loss		10		dB
Pdiss	Dissipated Power at Output power average ≈23dBm		3		W
P <sub>5dB</sub>	Output power at 5dB gain compression		31		dBm

These values are representative of onboard measurements as defined on the drawing in paragraph "Evaluation mother board"

### Electrical Characteristics – RX Mode

Tamb.= +25°C, VdL=VgL = 4V @ IdL = 60mA

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	24.25		30.5	GHz
Gain	Linear Gain		18		dB
NF	Noise Figure		3.25		dB
RL <sub>in</sub>	Input return loss		12		dB
RL <sub>out</sub>	Output return loss		17		dB
P1dB	Input power at 1dB gain comp		-7		dBm

These values are representative of onboard measurements as defined on the drawing in paragraph "Evaluation mother board".

#### Advanced Information

### Typical Bias Conditions

Symbol	Parameter	Tx mode	Rx mode	Unit
SW	Switch control voltage	0	20	V
Vg1L	LNA 1 <sup>st</sup> stage gate voltage	0	4	V
VdL	LNA drain voltage	0	4	V
Vg1d	Driver 1 <sup>st</sup> stage gate voltage	4	0	V
Vd1d	Driver 1 <sup>st</sup> stage drain voltage	4	0	V
Vg2d	Driver 2 <sup>nd</sup> stage gate voltage	4	0	V
Vd2d	Driver 2 <sup>nd</sup> stage drain voltage	4	0	V
Vg12	HPA gate voltage (quiescent biasing)	-3.1	0	V
Vd12	HPA drain voltage	25	0	V
Is	DC Switch control current Max. Switch control current vs. Pin max.	0	0	mA
		1	1	
IgL	DC LNA gate current (quiescent biasing) Max. Driver gate current vs. Pin max.	0	8	mA
		0	8	
IdL	DC LNA drain current (quiescent biasing) Max. Driver drain current vs. Pin max.	0	60	mA
		0	70	
Igd	DC Driver gate current (quiescent biasing) Max. Driver gate current vs. Pin max.	5	0	mA
		5	0	
Idd	DC Driver drain current (quiescent biasing) Max. Driver drain current vs. Pin max.	130	0	mA
		175	0	
I <sub>g12</sub>	DC HPA gate current (quiescent biasing) Max. HPA gate current vs. Pin max.	0.001	0	mA
		0.1	0	
Id <sub>12</sub>	DC HPA drain current (quiescent biasing) Max. HPA drain current vs. Pin max.	40	0	mA
		500	0	

#### Advanced Information

**Absolute Maximum Ratings – TX Mode <sup>(1)</sup>**

Tamb.= +25°C

Symbol	Parameter	Values	Unit
Vd12	HPA Drain bias voltage	27	V
Vg12	HPA Gate bias voltage	-9 , -2	V
Id12	HPA drain current at saturated power	700	mA
Vd1d/Vd2d	Driver 1 <sup>st</sup> /2 <sup>nd</sup> stage drain voltage	4.5	V
Vg1d/Vg2d	Driver 1 <sup>st</sup> /2 <sup>nd</sup> stage gate voltage	4.5	V
Idd	Driver drain current at saturated power	200	mA
SW	Switch Control voltage	0	V
Pin	Maximum Input power	+10	dBm
Tc	Operating temperature range	-40 to +95	°C
Tstg	Storage temperature range	-55 to +125	°C

<sup>(1)</sup> Operation of this device above anyone of these parameters may cause permanent damage.

**Absolute Maximum Ratings – RX Mode <sup>(2)</sup>**

Tamb.= +25°C

Symbol	Parameter	Values	Unit
VdL	Drain bias voltage	4.5	V
VgL	Gate bias voltage	4.5	V
IdL	LNA drain current at saturated power	100	mA
SW	Switch Control voltage	20	V
Pin	Maximum Input power	-3	dBm
Tc	Operating temperature range	-40 to +95	°C
Tstg	Storage temperature range	-55 to +150	°C

<sup>(2)</sup> Operation of this device above anyone of these parameters may cause permanent damage.

**Recommended Operating – TX Mode** <sup>(3) (4)</sup>

Tamb.= +25°C

Symbol	Parameter	Values	Unit
Vd12	HPA Drain bias voltage	18 to 25	V
Vg12	HPA Gate bias voltage (quiescent biasing)	-3.1	V
Id12	HPA drain quiescent bias current	40	mA
Vd1d/Vd2d	Driver 1 <sup>st</sup> /2 <sup>nd</sup> stage drain voltage	4	V
Vg1d/Vg2d	Driver 1 <sup>st</sup> /2 <sup>nd</sup> stage gate voltage	4	V
Idd	Driver drain quiescent bias current	130	mA
SW	Switch Control voltage	0	V
Pin	Maximum Input power	+8	dBm

<sup>(3)</sup> Electrical performances are defined for specified test conditions<sup>(4)</sup> Electrical performances are not guaranteed over all recommended operating conditions
**Recommended Operating – RX Mode** <sup>(5) (6)</sup>

Tamb.= +25°C

Symbol	Parameter	Values	Unit
Vd12	HPA Drain bias voltage	18 to 25	V
Vg12	HPA Gate bias voltage	-5.0	V
VdL	Drain bias voltage	4	V
VgL	Gate bias voltage	4	V
IdL	LNA drain quiescent bias current	60	mA
SW	Switch Control voltage	20	V
Pin	Maximum Input power	-3	dBm

<sup>(5)</sup> Electrical performances are defined for specified test conditions<sup>(6)</sup> Electrical performances are not guaranteed over all recommended operation conditions
**Temperature Range**

Tc	Operating temperature range (QFN backside)	-40 to +85	°C
Tstg	Storage temperature range	-55 to +150	°C

**Advanced Information**

## Biassing procedure

### Mode 1 – Tx mode

Device Power Up instructions:

#### HPA & Switch

1. Ground the device:  $I_{D12} = 0A$
2. Set  $V_{g12}$  to -5.0V:  $I_{D12} = 0A$
3. Set  $V_{d12}$  to 0V (*pinch off test*):  $I_{D12} = 0A$
4. Set  $V_{d12}$  to 25V (*nominal bias voltage*):  $I_{D12} = 0A$
5. Set SW to 0V

#### Driver

1. Set  $V_{g1d}$  &  $V_{d1d}$  &  $V_{g2d}$  &  $V_{d2d}$  to 0V (*pinch off test*):  $I_{dd} = 0A$  /  $I_{gd} = 0A$
2. Set  $V_{g1d}$  &  $V_{d1d}$  &  $V_{g2d}$  &  $V_{d2d}$  to 4V (*nominal bias voltage*):  $I_{dd} = 130mA$  /  $I_{gd} = 8mA$   
*N.B: in order to protect the product, please to bias:*
  - at the same time the 4 accesses,
  - or, in first, the drain accesses, then to increase slowly  $V_{g1d}$  &  $V_{g2d}$  up to 4V
3. Increase slowly  $V_{g12}$  up to quiescent bias drain current  $I_{D12} = 40mA$
4. Apply RF input power

Device Power Down instructions:

1. Remove RF input power
2. Decrease  $V_{g12}$  down to -5.0V
3. Decrease  $V_{g1d}$  &  $V_{d1d}$  &  $V_{g2d}$  &  $V_{d2d}$  down to 0V  
*N.B: in order to protect the product, please to bias:*
  - at the same time the 4 accesses,
  - or, in first, the drain accesses, then to decrease slowly  $V_{g1d}$  &  $V_{g2d}$  down to 0V
4. Remove SW
5. Decrease  $V_{d12}$  down to 0V

## Biassing procedure

### Mode 2 – Rx mode

Device Power Up instructions:

#### HPA & Switch

1. Ground the device
2. Set SW to 20V
3. Set Vg12 to -5V:  $I_{D12} = 0A$   
Vd12 = 25V

#### LNA

1. Set Vg1L & VdL to 0V (*pinch off test*)
2. Set Vg1L & VdL to 4V (*nominal bias voltage*)  
*N.B: in order to protect the product, please to bias:*
  - at the same time the 2 accesses,
  - or, in first, VdL, then to increase slowly Vg1L up to 4V
3. Apply RF input power

Device Power Down instructions:

1. Remove RF input power
2. Decrease Vg1L & VdL down to 0V  
*N.B: in order to protect the product, please to bias:*
  - at the same time the 2 accesses,
  - or, in first, the drain accesses, then to decrease slowly Vg1L down to 0V
3. Remove SW

Notes:

It is possible to begin the test measurement with Mode 1 or Mode 2.

In order to reduce DC biasing, be sure to

- in case of Mode 2 / Rx mode use:

set HPA Vg12 to -5V, decrease Vd12 to 0V and set Vg12 to 0V

set Driver Vg1d, Vg2d & Vd1d, Vd2d to 0V

- in case of Mode 1 / Tx mode use:

set LNA Vg1L & VdL to 0V

CHC6054-QQA could be used on only one mode in the same time

## Advanced Information

**Typical Board Measurements**

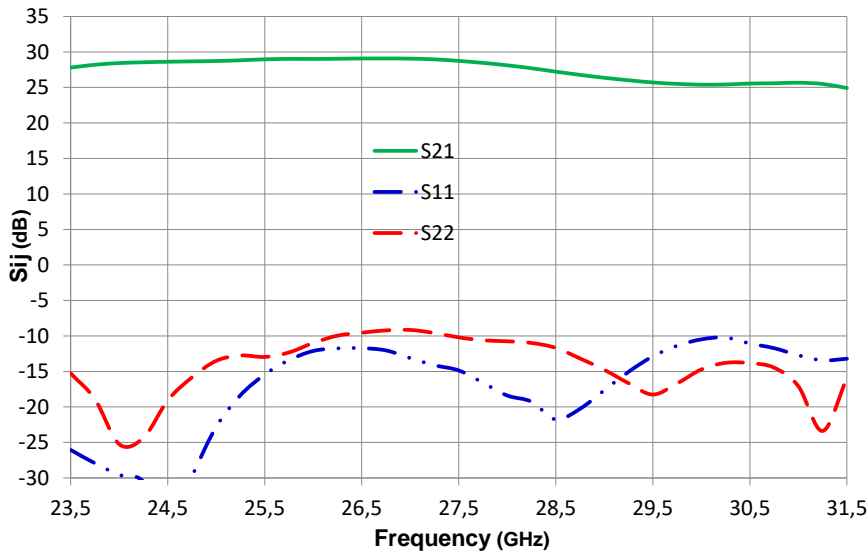
Tamb.= +25°C

Losses due to board are de-embedded. Measurements are given in the QFN access plan

**Gain & Return Losses versus Frequency – TX Mode**

Vd12 = +25V, Vg12 set in order to get Id12 = 40mA

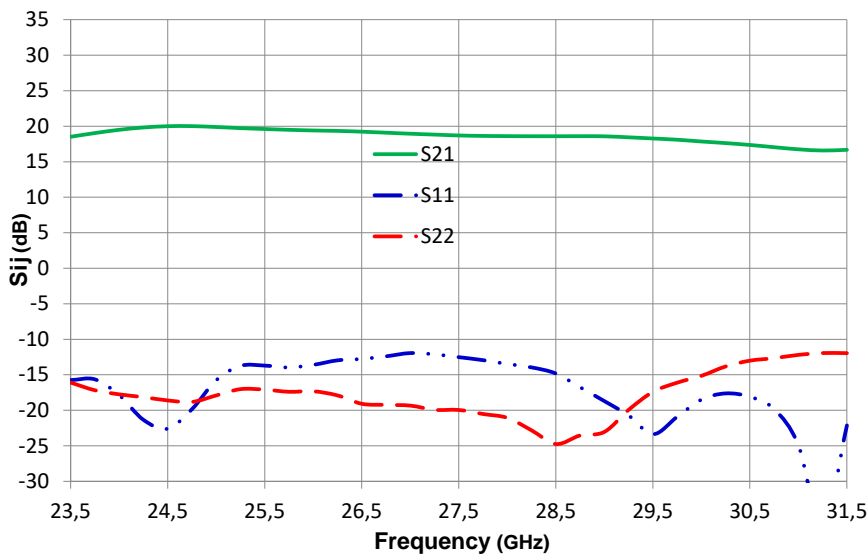
SW = 0V, VdL=Vg1L=0V, Vd1d = Vd2d = Vg1d = Vg2d = 4V



**Gain & Return Losses versus Frequency – RX Mode**

Vd12 = +25V, Vg12 = -5V in order to get Id12 = 0mA

SW = 20V, VdL=Vg1L=4V, Vd1d = Vd2d = Vg1d = Vg2d = 0V



Advanced Information



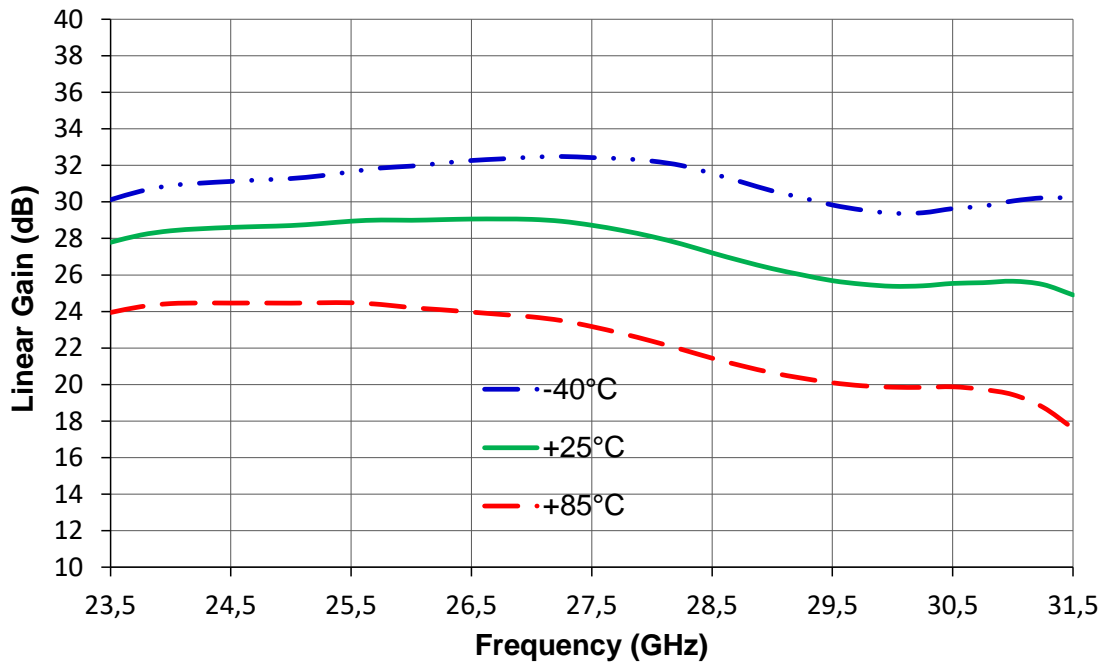


**Typical Board Measurements – TX MODE**

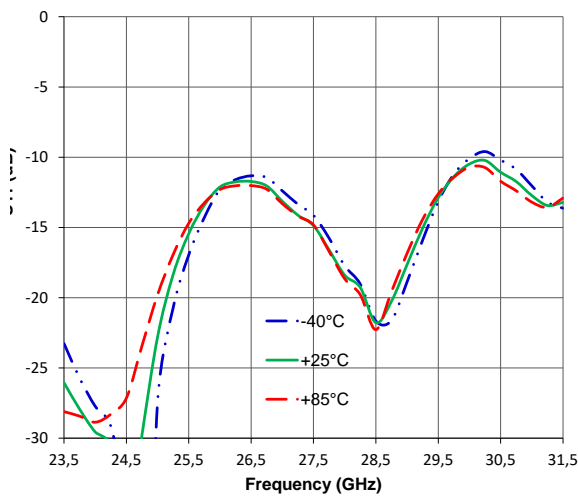
Tamb.= +25°C, SW = 0V, Vd12 = 25V, Vg12 set in order to get Id12 = 40mA  
Vd1d = Vd2d = Vg1d = Vg2d = 4V, VdL=Vg1L=0V

Losses due to board are de-embedded. Measurements are given in the QFN access plan

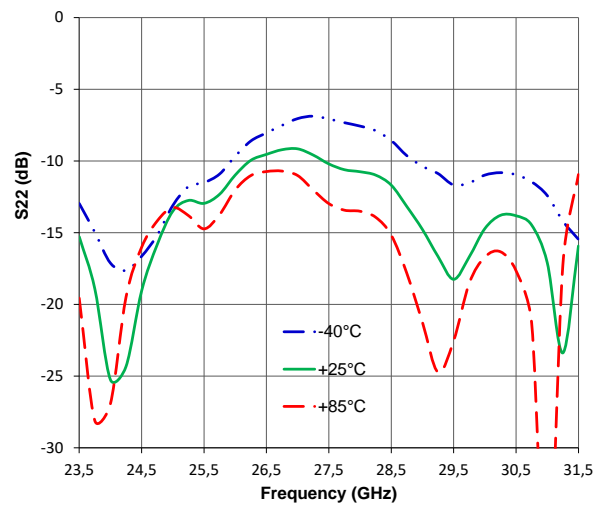
**Gain versus Frequency in Temperature**



**Input Return Losses versus Frequency in Temperature**



**Output Return Losses versus Frequency In Temperature**



**Advanced Information**



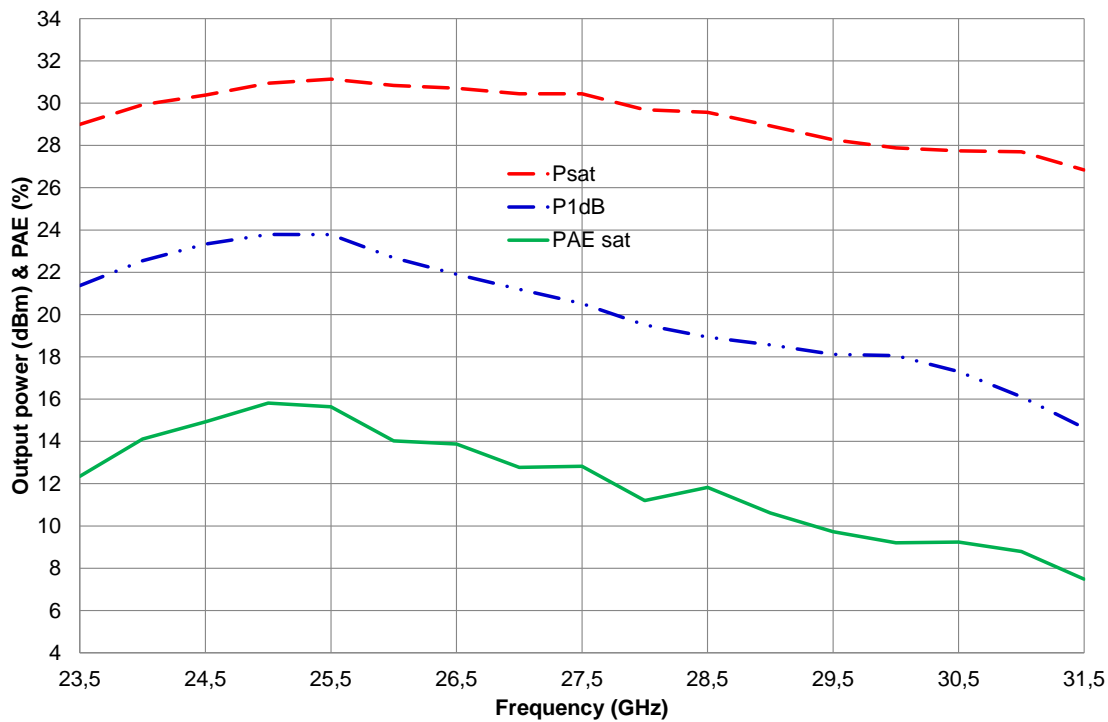
### Typical Board Measurements – TX MODE

Tamb.= +25°C, SW = 0V, Vd12 = 25V, Vg12 set in order to get Id12 = 40mA

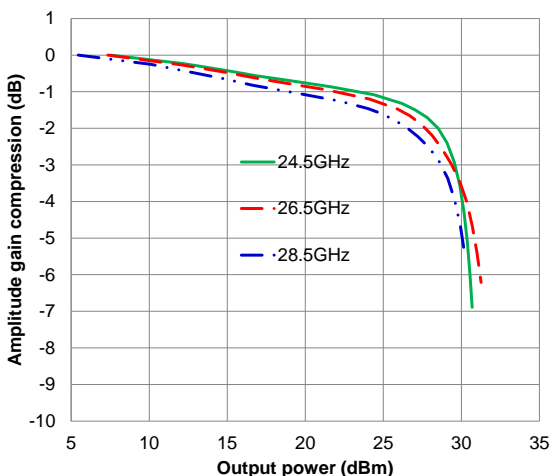
Vd1d = Vd2d = Vg1d = Vg2d = 4V, VdL=Vg1L=0V

Losses due to board are de-embedded. Measurements are given in the QFN access plan

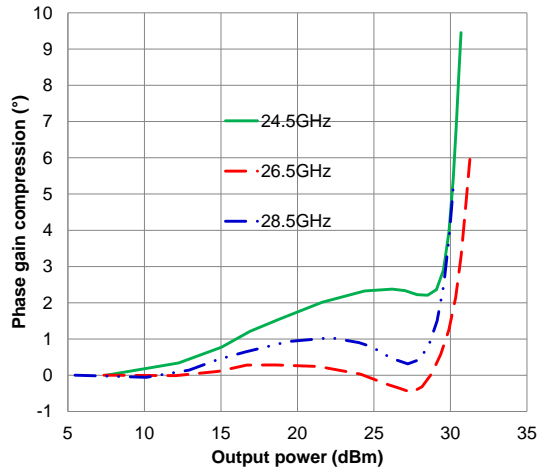
**Output Power & PAE versus Frequency**



**Gain Amplitude versus Output Power**



**Gain Phase versus Output Power**



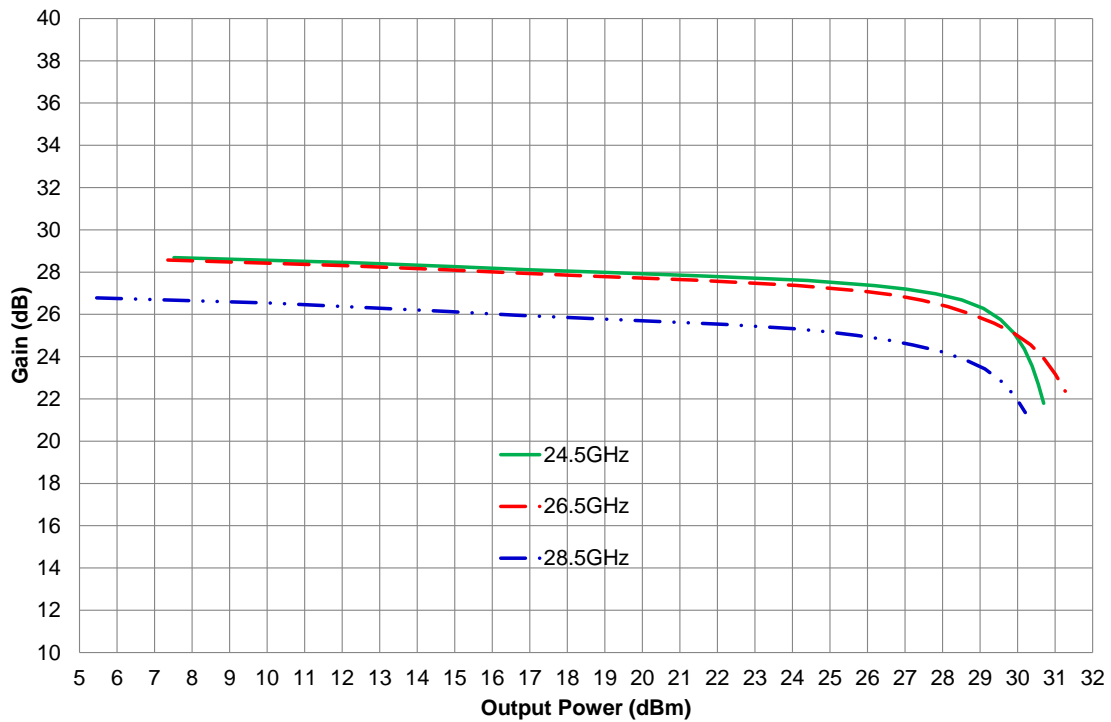
### Advanced Information

## Typical Board Measurements – TX MODE

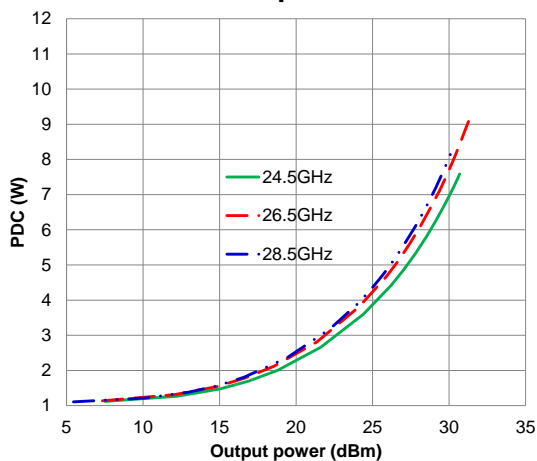
Tamb.= +25°C, SW = 0V, Vd12 = 25V, Vg12 set in order to get Id12 = 40mA  
Vd1d = Vd2d = Vg1d = Vg2d = 4V, VdL=Vg1L=0V

Losses due to board are de-embedded. Measurements are given in the QFN access plan

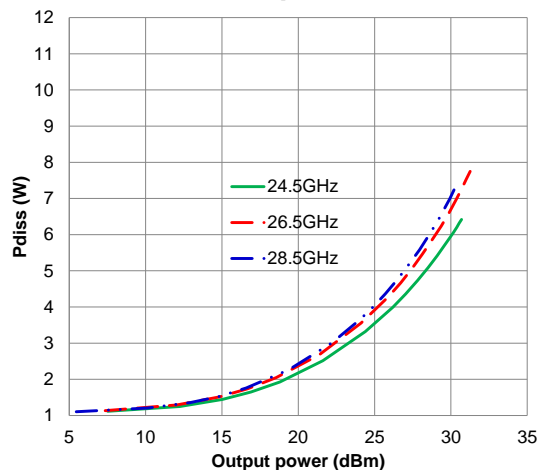
**Gain versus Output Power**



**DC Power Consumption versus Output Power**



**Dissipated Power versus Output Power**



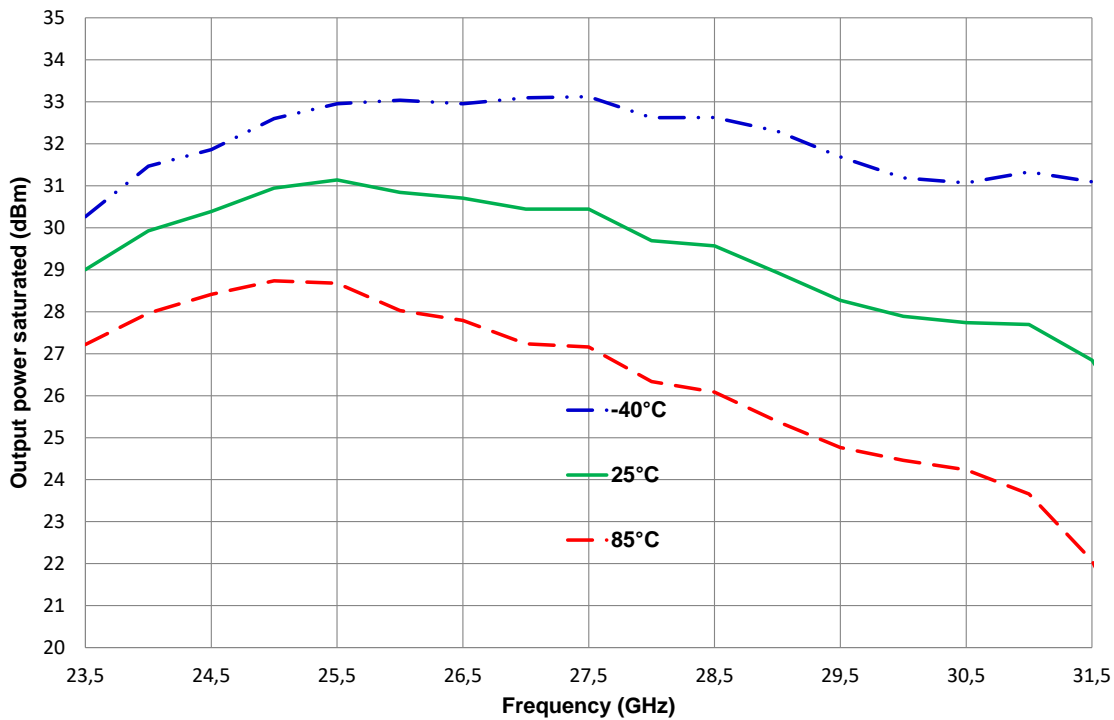
### Advanced Information

**Typical Board Measurements – TX MODE**

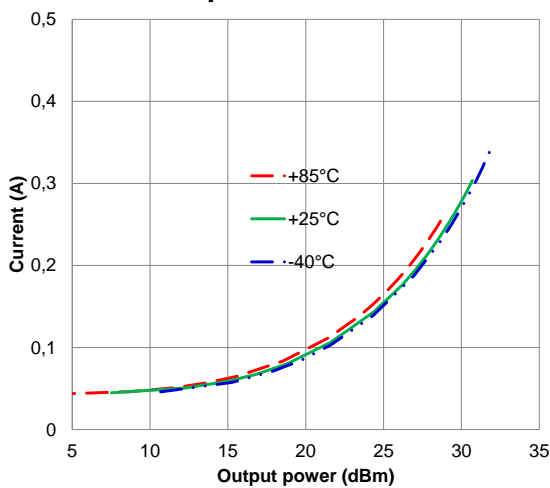
SW = 0V, Vd12 = 25V, Vg12 set in order to get Id12 = 40mA  
Vd1d = Vd2d = Vg1d = Vg2d = 4V, VdL=Vg1L=0V

Losses due to board are de-embedded. Measurements are given in the QFN access plan

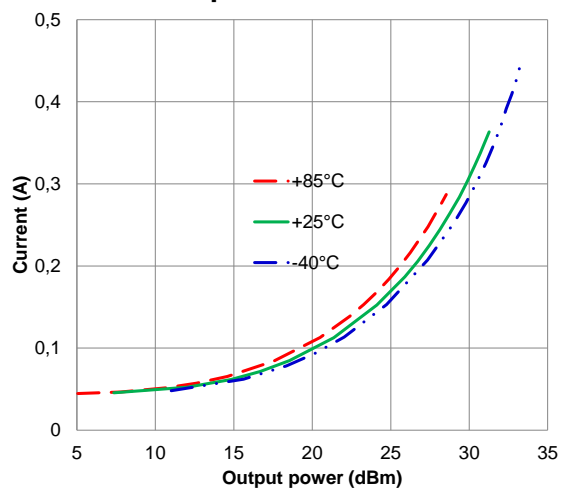
**Output Power saturated versus Frequency in Temperature**



**HPA Drain Current versus Output Power @24.5GHz**



**HPA Drain Current versus Output Power @26.5GHz**



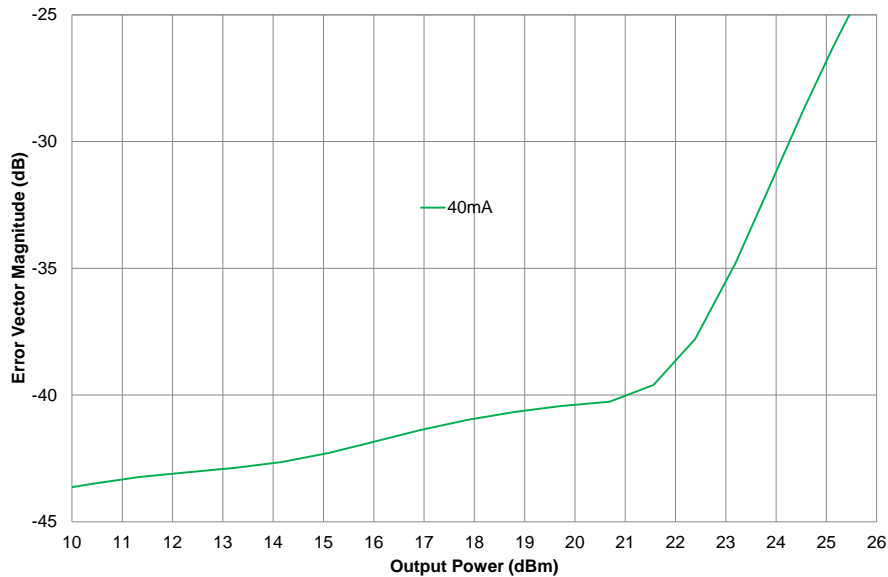
**Advanced Information**



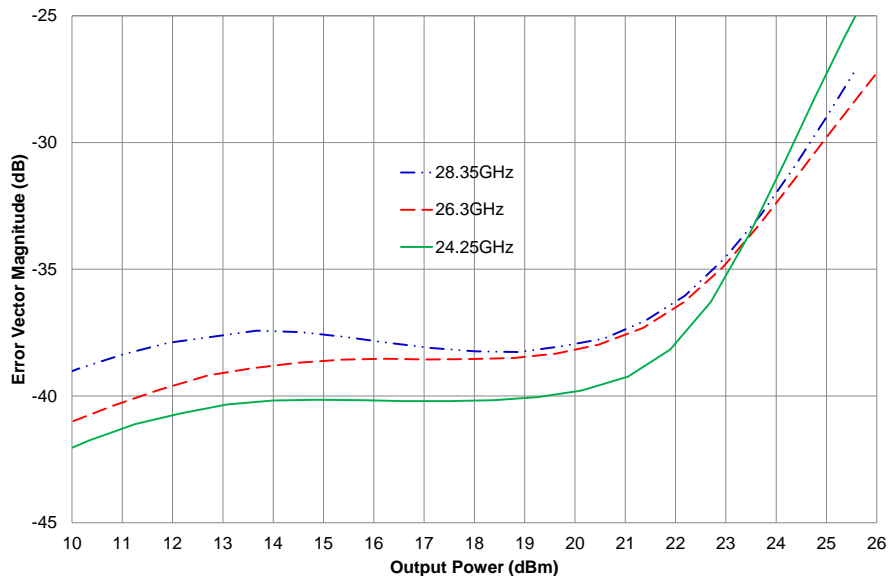
**Typical Board Measurements – TX MODE**

Tamb.= +25°C, SW = 0V, Vd12 = 25V, Vg12 set in order to get Id12  
 Vd1d = Vd2d = Vg1d = Vg2d = 4V, VdL=Vg1L=0V ; QAM Modulation **without DPD**  
 Losses due to board are de-embedded. Measurements are given in the QFN access plan

**Error Vector Magnitude versus Output Power and Idq**  
 RF\_Freq = 24.25GHz ; Channel Spacing =56MHz, 4QAM



**Error Vector Magnitude versus Output Power and RF Frequency**  
 Idq = 40mA ; Channel Spacing =56MHz, 4QAM

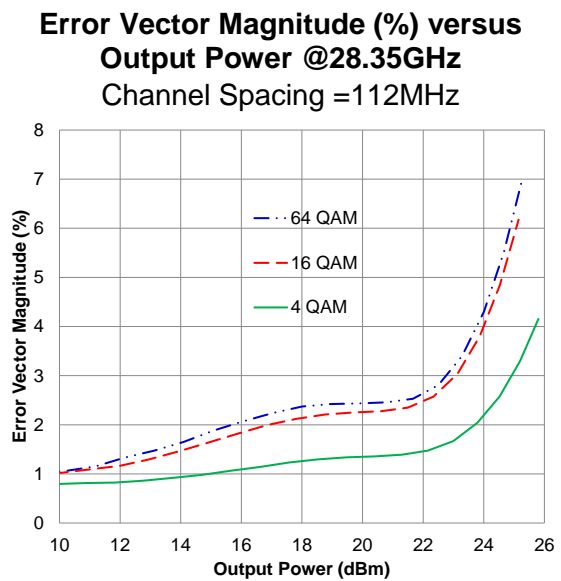
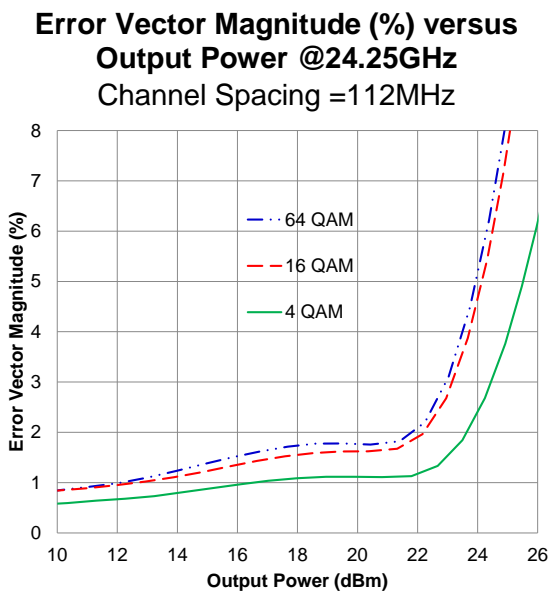
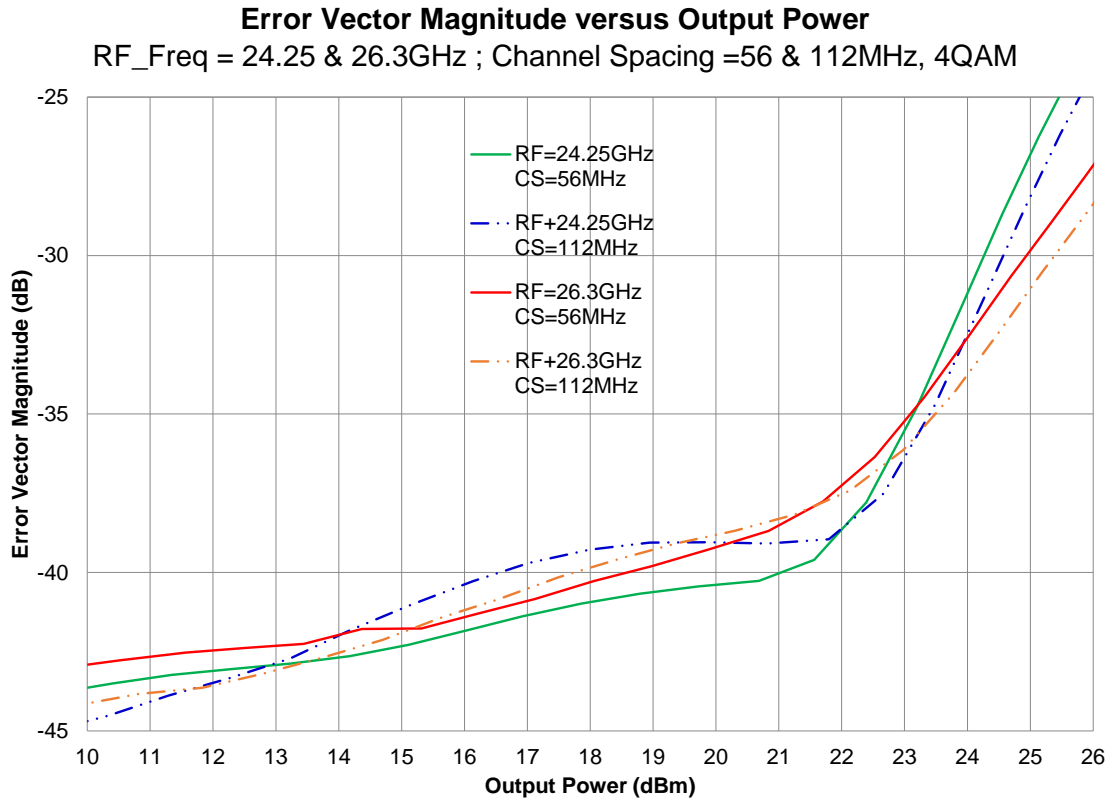


Advanced Information



**Typical Board Measurements – TX MODE**

Tamb.= +25°C, SW = 0V, Vd12 = 25V, Vg12 set in order to get Id12 = 40mA  
 Vd1d = Vd2d = Vg1d = Vg2d = 4V, VdL=Vg1L=0V ; QAM Modulation **without DPD**  
 Losses due to board are de-embedded. Measurements are given in the QFN access plan



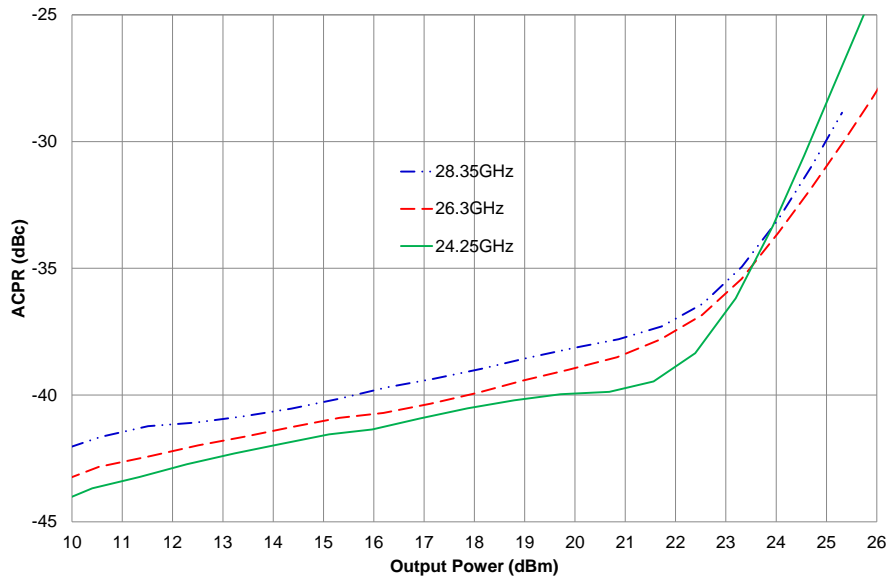
Advanced Information



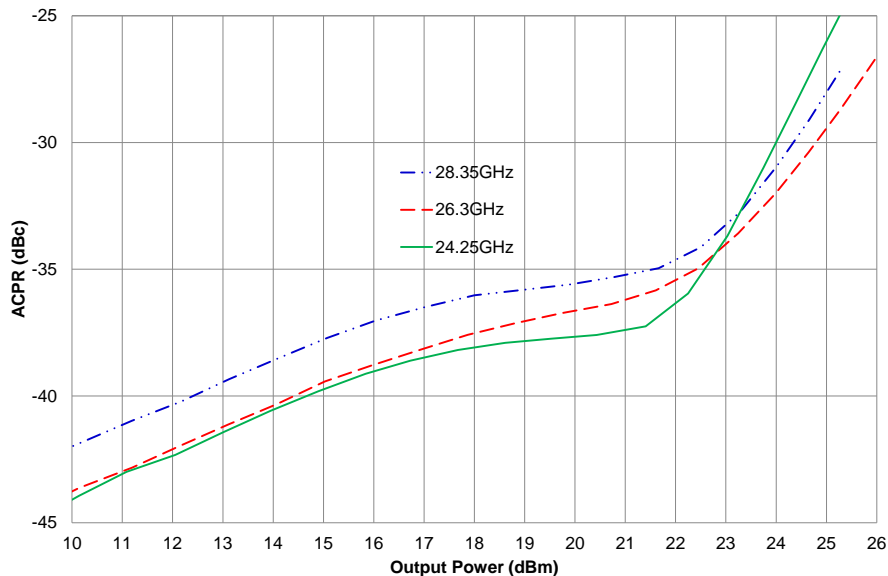
## Typical Board Measurements – TX MODE

Tamb.= +25°C, SW = 0V, Vd12 = 25V, Vg12 set in order to get Id12 = 40mA  
 Vd1d = Vd2d = Vg1d = Vg2d = 4V, VdL=Vg1L=0V ; QAM Modulation **without DPD**  
 Losses due to board are de-embedded. Measurements are given in the QFN access plan

**ACPR versus Output Power and RF Frequency**  
 Channel Spacing =56MHz, 4QAM



**ACPR versus Output Power and RF Frequency**  
 Channel Spacing =112MHz, 64QAM



### Advanced Information



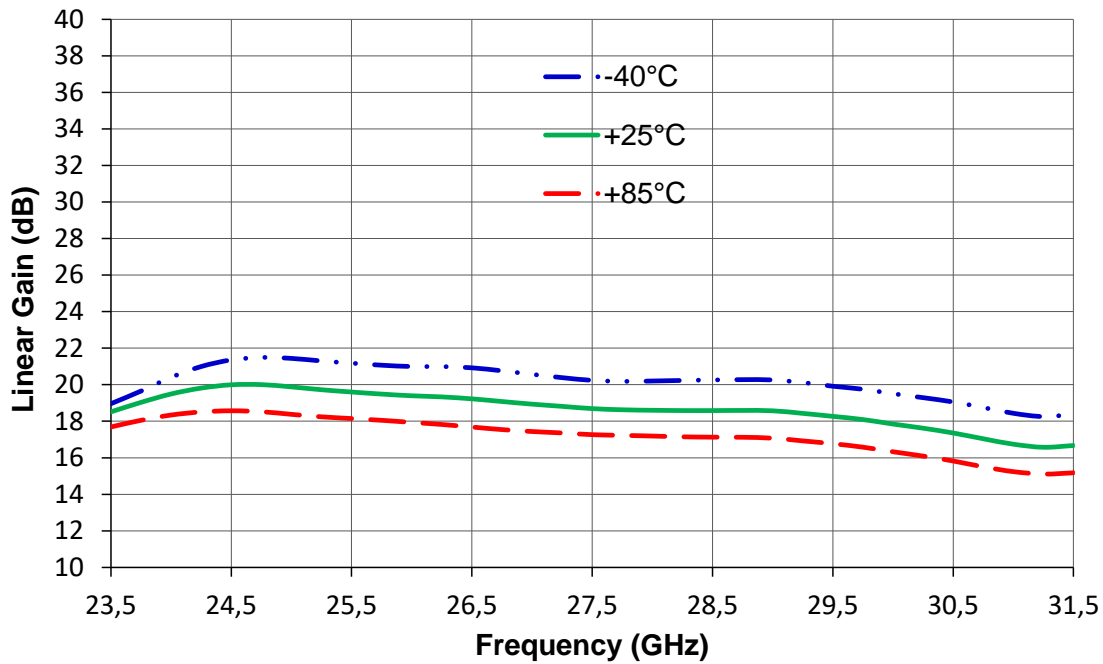
**Typical Board Measurements – RX MODE**

SW = +20V, Vd12 = 25V, Vg12 = -5V in order to get Id12 = 0mA

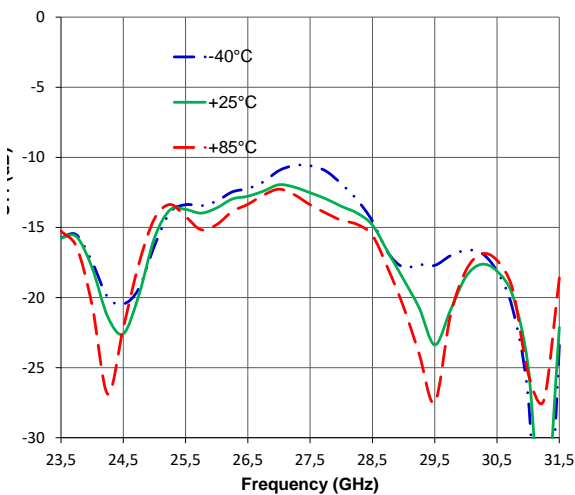
Vd1d = Vd2d = Vg1d = Vg2d = 0V, VdL=Vg1L=4V

Losses due to board are de-embedded. Measurements are given in the QFN access plan

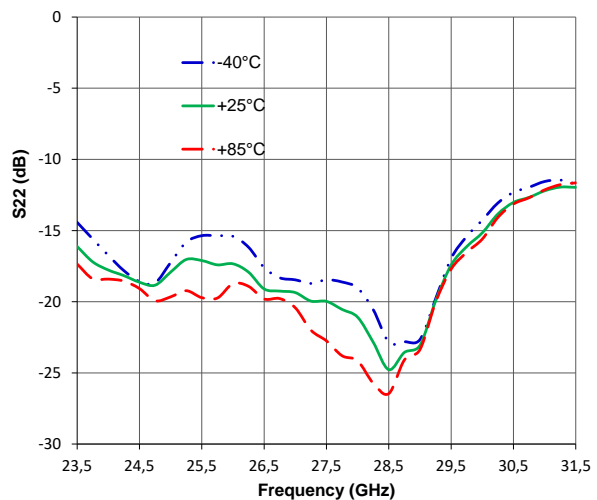
**Gain versus Frequency in Temperature**



**Input Return Losses versus Frequency In Temperature**



**Output Return Losses versus Frequency In Temperature**



**Advanced Information**





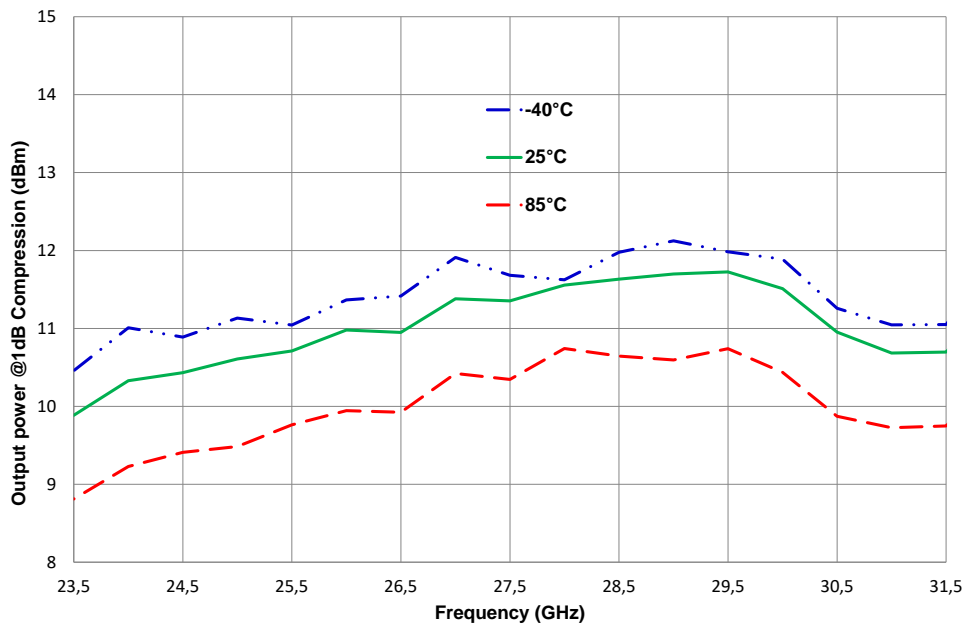
**Typical Board Measurements – RX Mode**

SW = +20V, Vd12 = 25V, Vg12 = -5V in order to get Id12 = 0mA

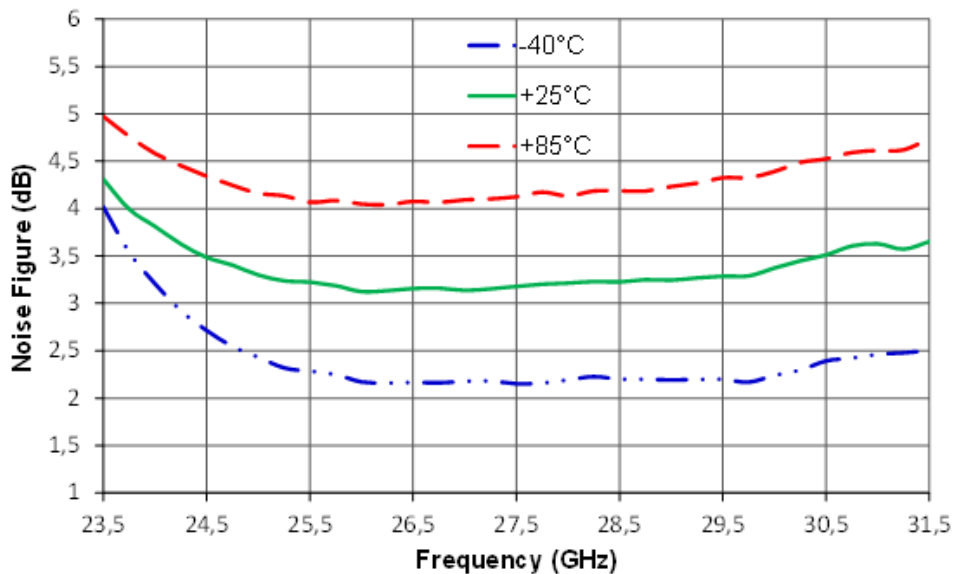
Vd1d = Vd2d = Vg1d = Vg2d = 0V, VdL=Vg1L=4V

Losses due to board are de-embedded. Measurements are given in the QFN access plan

**Output Power at 1dB compression versus Frequency in Temperature**



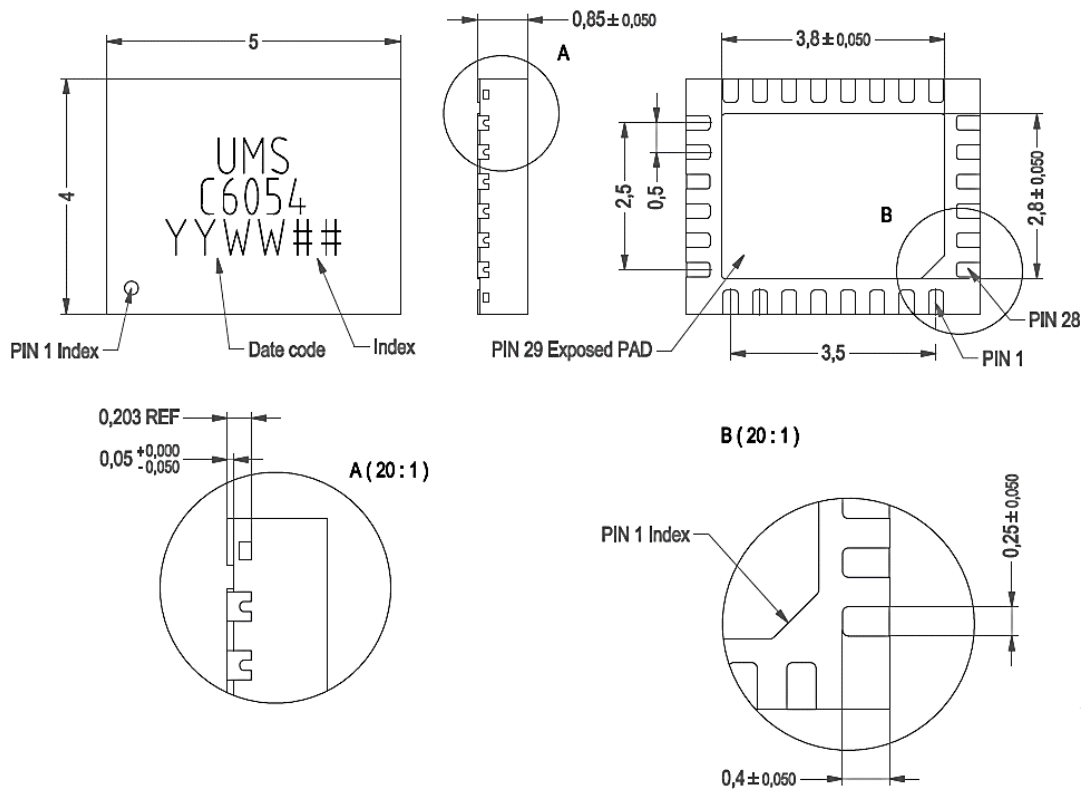
**Noise Figure versus Frequency in Temperature**



Advanced Information



**Package outline (1)**



Matte tin, Lead Free	(Green)	1- GND <sup>(2)</sup>	11- GND <sup>(2)</sup>	21- Vg12
Units :	mm	2- Nc	12- GND <sup>(2)</sup>	22- Vd12
From the standard :	JEDEC	3- SW	13- Input TX	23- GND <sup>(2)</sup>
	MO-220	4- GND <sup>(2)</sup>	14- GND <sup>(2)</sup>	24- Nc
	(VGGD)	5- Vg1L	15- Vg1d	25- GND <sup>(2)</sup>
	29- GND	6- VdL	16- Vd1d	26- GND <sup>(2)</sup>
		7- GND <sup>(2)</sup>	17- Vg2d	27- Common
		8- Nc	18- Vd2d	28- GND <sup>(2)</sup>
		9- GND <sup>(2)</sup>	19- GND <sup>(2)</sup>	
		10- Output RX	20- GND <sup>(2)</sup>	

(1) The package outline drawing included to this document is given for indication. Refer to the application note AN0017 (<https://www.ums-rf.com>) for exact package dimensions.

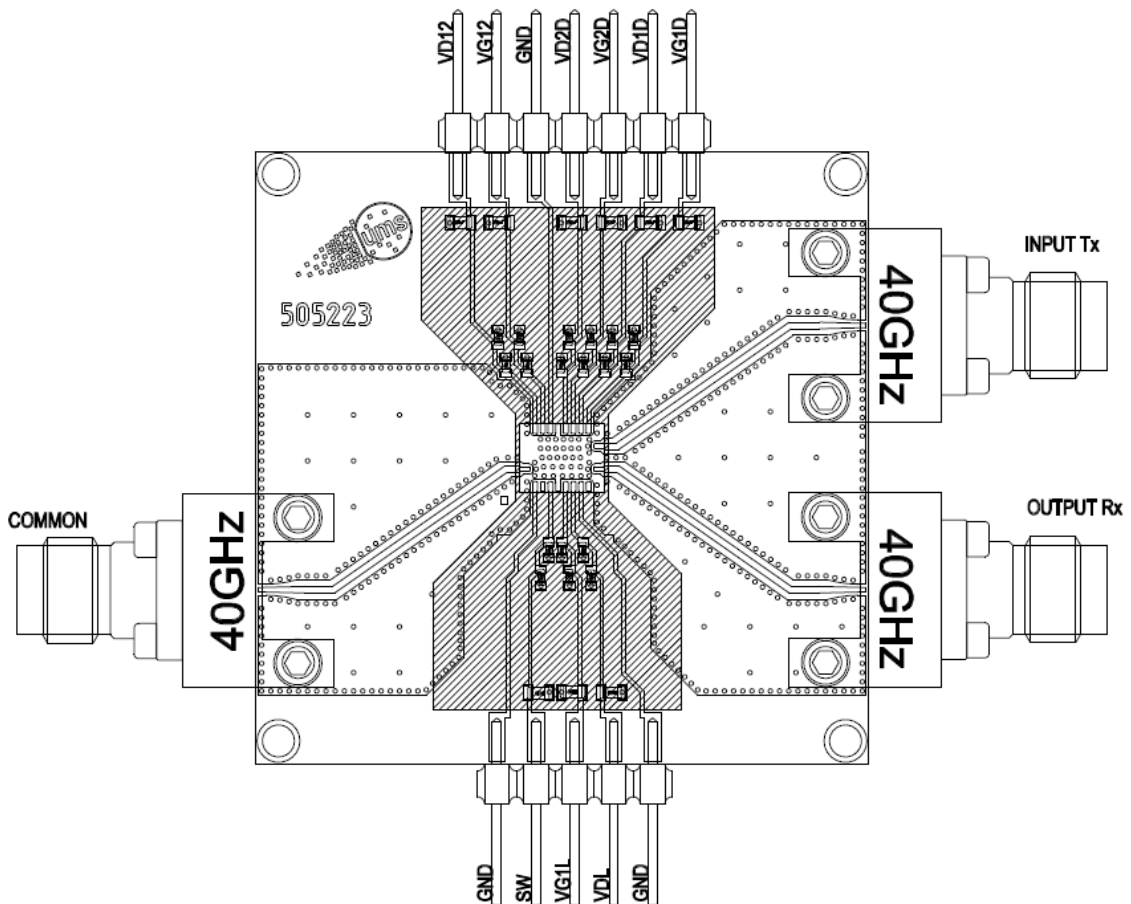
(2) It is strongly recommended to ground all pins marked “GND” through the PCB board. Ensure that the PCB board is designed to provide the best possible ground to the package.

**Advanced Information**

## Evaluation mother board

Compatible with the proposed footprint.

- Based on typically Ro4003 / 8mils or equivalent.
- Using a micro-strip to coplanar transition to access the package.
- Recommended for the implementation of this product on a module board.
- Decoupling capacitors: 100pF  $\pm$ 5%, 10nF  $\pm$ 10% and 1 $\mu$ F  $\pm$ 10% are recommended for all DC accesses.
- See application note AN0017 for details.



Note: All board measurements are performed using shielded cables, even for DC bias, to ensure safe operation.

### Advanced Information

## ESD Notes

ESD – Human Body Model (HBM)

Class 1A / 250 volts to < 500 volts <sup>(1)</sup> <sup>(2)</sup>

ESD – Machine Model (MM)

Class M1 / < 100 volts <sup>(1)</sup>

Class M2 / 100 volts up to 200 volts <sup>(2)</sup>

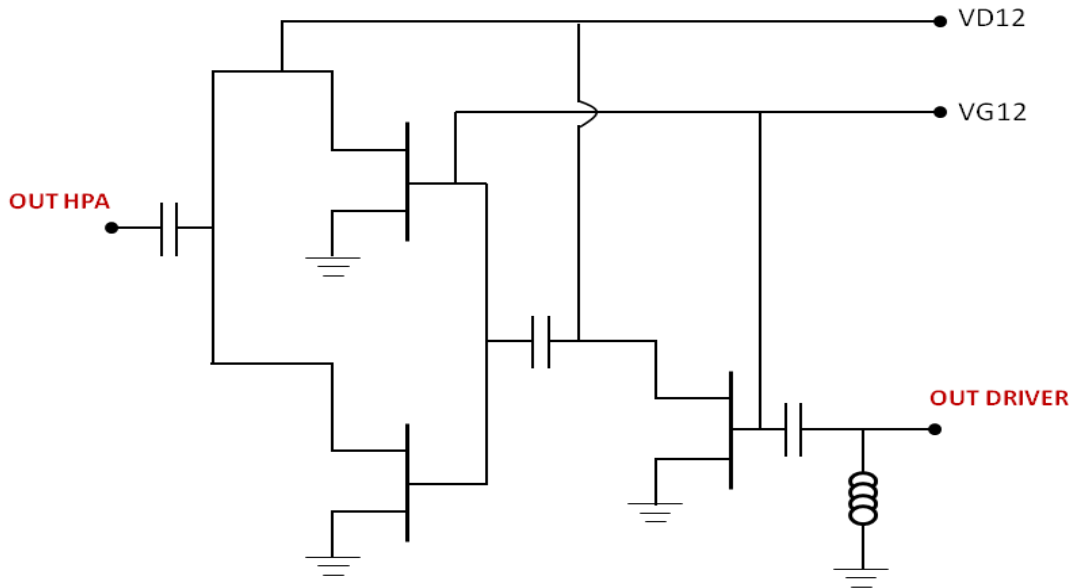
<sup>(1)</sup> from pin #22 (Vd12) ESDA / JEDEC JESD22-A114

<sup>(2)</sup> from pin #10 (Output\_RX) ESDA / JEDEC JESD22-A115

The DC connections do not include any decoupling capacitor in package, therefore it is mandatory to provide a good external DC decoupling (100pF mandatory and 10nF & 1μF if possible) on the PC board, as close as possible to the package.

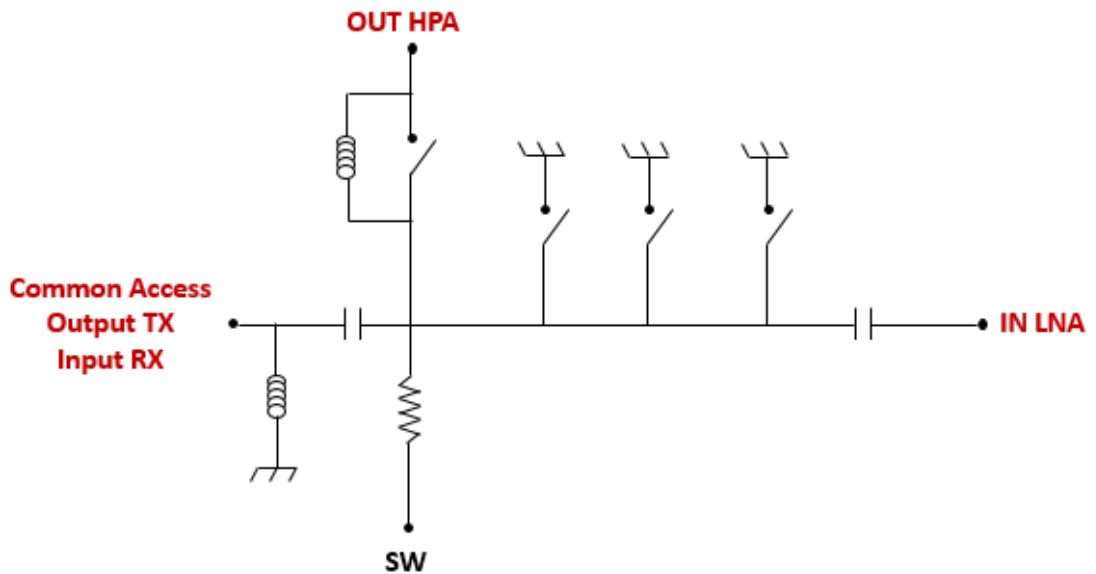
### Advanced Information

**HPA DC Schematic**



Vg12 # -3.1V, Vd12 = 25V, Id12 = 40mA

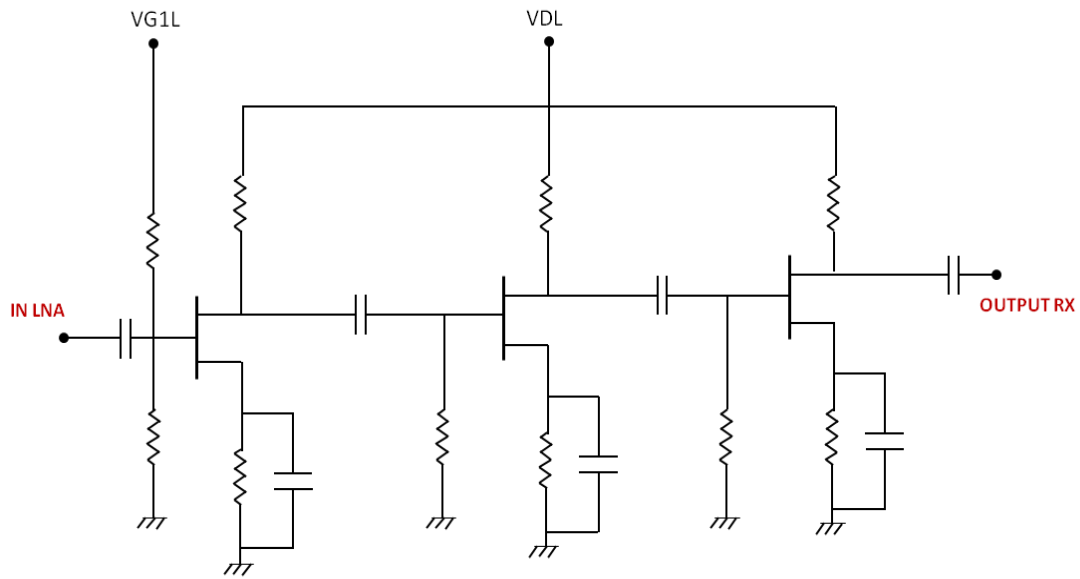
**Switch DC Schematic**



TX mode: SW = 0V  
RX mode: SW = +20V

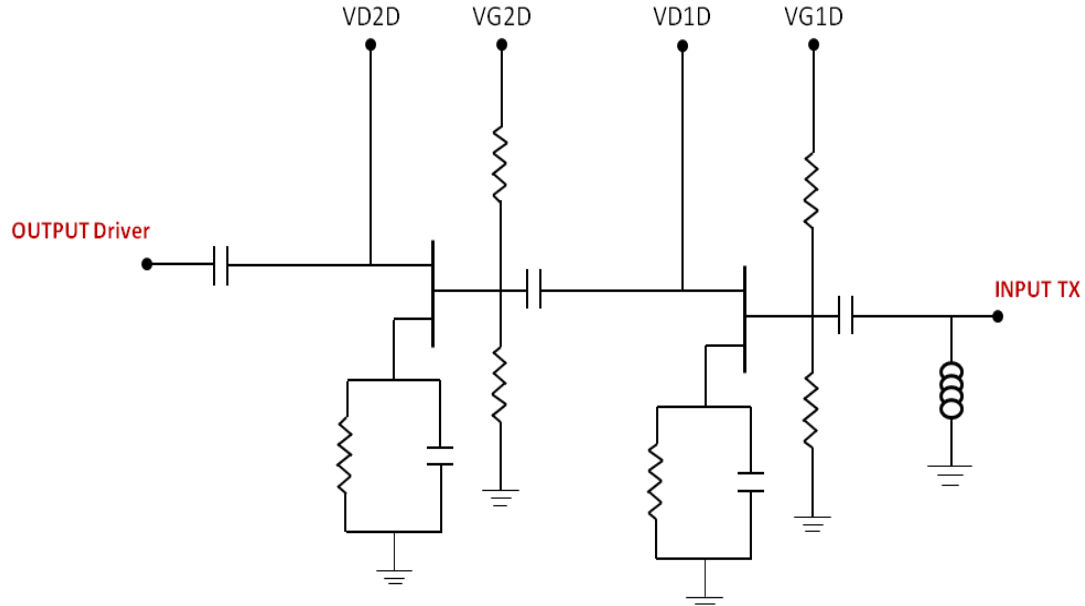
**Advanced Information**

### LNA DC Schematic



$V_{g1L} = 4V$ ,  $V_{dL} = 4V$ ,  $I_{dL} = 60mA$

### Driver DC Schematic



$V_{d1d} = V_{d2d} = 4V$ ,  $V_{g1d} = V_{g2d} = 4V$ ,  $I_{d12d} = 130mA$

### Advanced Information